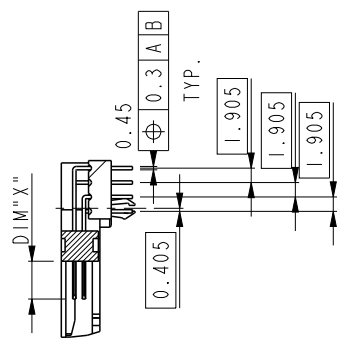
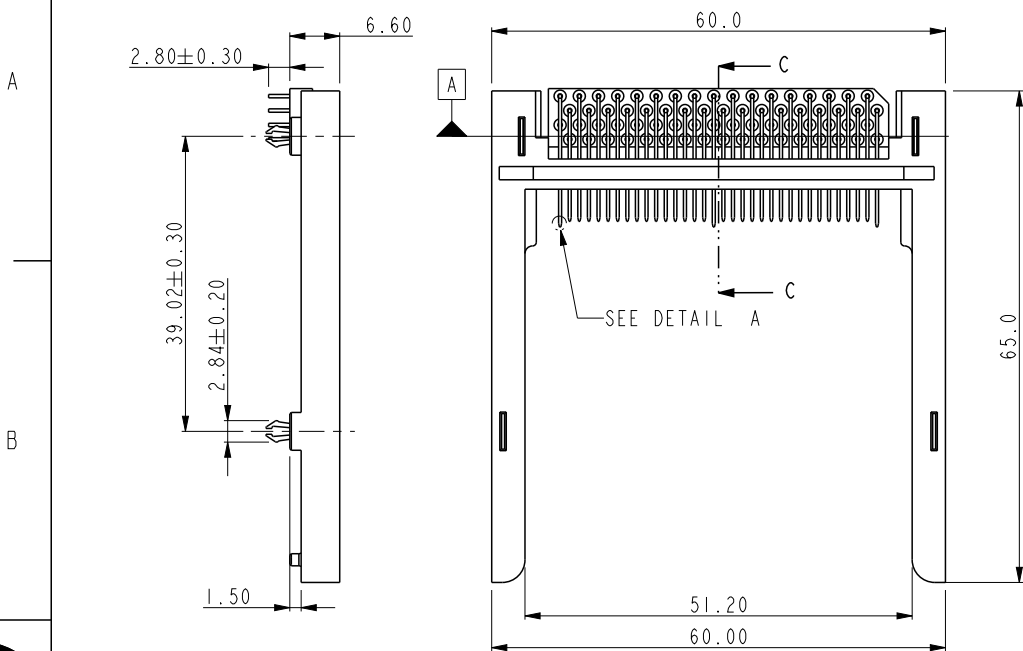
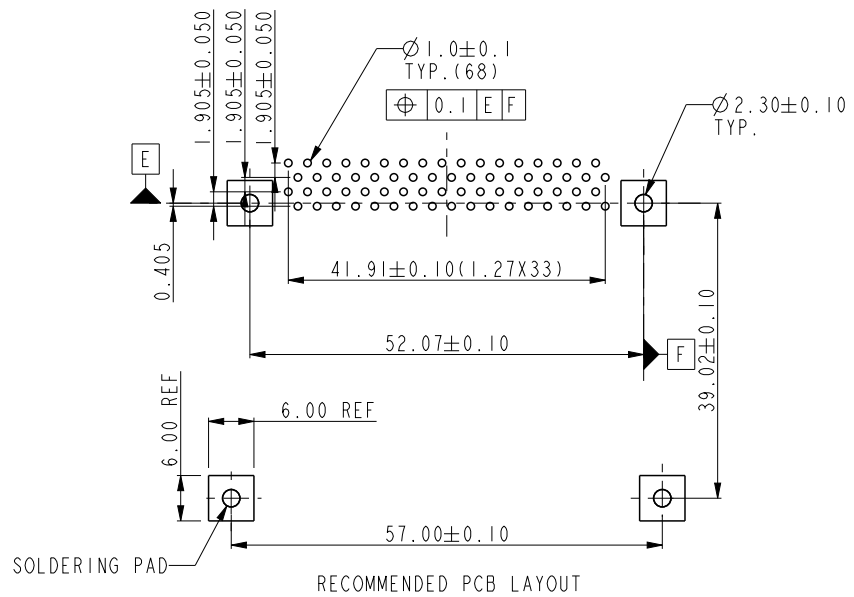
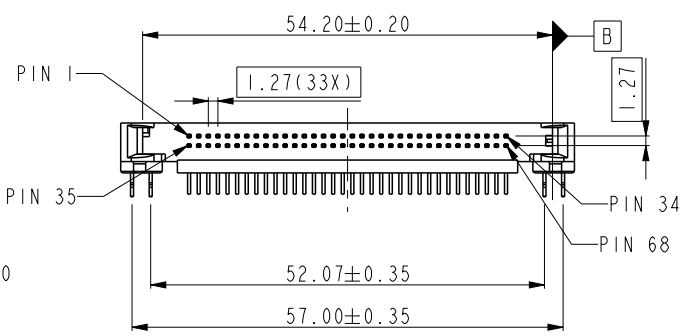
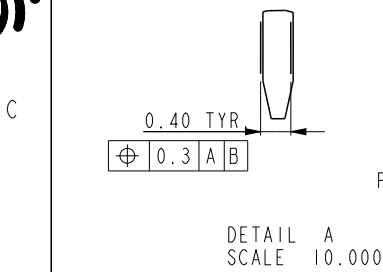


PRODUCT NO.	STAND OFF
10118309-015LF	1.5



- NOTE:
- 1.MATERIAL: HOUSING:HIGH TEMPERATURE THERMOPLASTIC
LOCATOR:HIGH TEMPERATURE THERMOPLASTIC
PIN- COPPER ALLOY
 - 2.FINISH(PIN)
 - a. ALL OVER : Ni UNDER PLATING 1.27um THICK MIN.
 - b. CONTACT AREA: Au 0.075um THK MIN.
 - c. PURE TIN PLATING 2.5um THICK MIN.
 3. IF LEAD FREE P/N, THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.60MM MINIMUM THICK CIRCUIT BOARD.
 4. LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBLED IN GS-22-008
 5. PRODUCT SPEC: 110-263

DIM X			
DIM	4.25±0.1	3.5±0.1	5.0±0.1
PIN NUMBER	OTHERS	36,67	1,17,34,35,51,68



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spec ref		dr Su-Hua Miao		2012/01/04		projection		MM		size A4		scale 1.000	
tolerance std		eng Su-Hua Miao		2012/01/17						ecn no		-	
TOLERANCES UNLESS OTHERWISE SPECIFIED		chr -		-						rel level		Released	
surface -		appr Rick Bian		2012/01/18		product family		-		rev		A	
ISO1302		linear		0.X ±0.3				title 68POS.HEADER ASS'Y PCMCIA HALOGEN-FREE 3.3V PRODUCT		dwg no 10118309		sheet 1 of 1	
		0.XX ±0.15											
		0.XXX ±0.08											
		angular		0° ±2°		www.fci.com		cat. no.		Product - Customer Drw		-	

ProjE File - REV C - 2009-06-09